



SOT1202

XSON6: extremely thin small outline package; no leads; 6 terminals; body 1.0 x 1.0 x 0.35 mm

8 February 2016

Package information

1. Package summary

Terminal position code	D (double)
Package type descriptive code	XSON6
Package type industry code	XSON6
Package style descriptive code	XSON (extremely thin small outline; no leads)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	6-4-2010

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	0.95	-	1	1.05	mm
E	package width	0.95	-	1	1.05	mm
A	seated height	[tbd]	-	[tbd]	0.35	mm
A ₂	package height	[tbd]	-	[tbd]	0.31	mm
e	nominal pitch	-	-	0.55	-	mm
n ₂	actual quantity of termination	-	-	6	-	

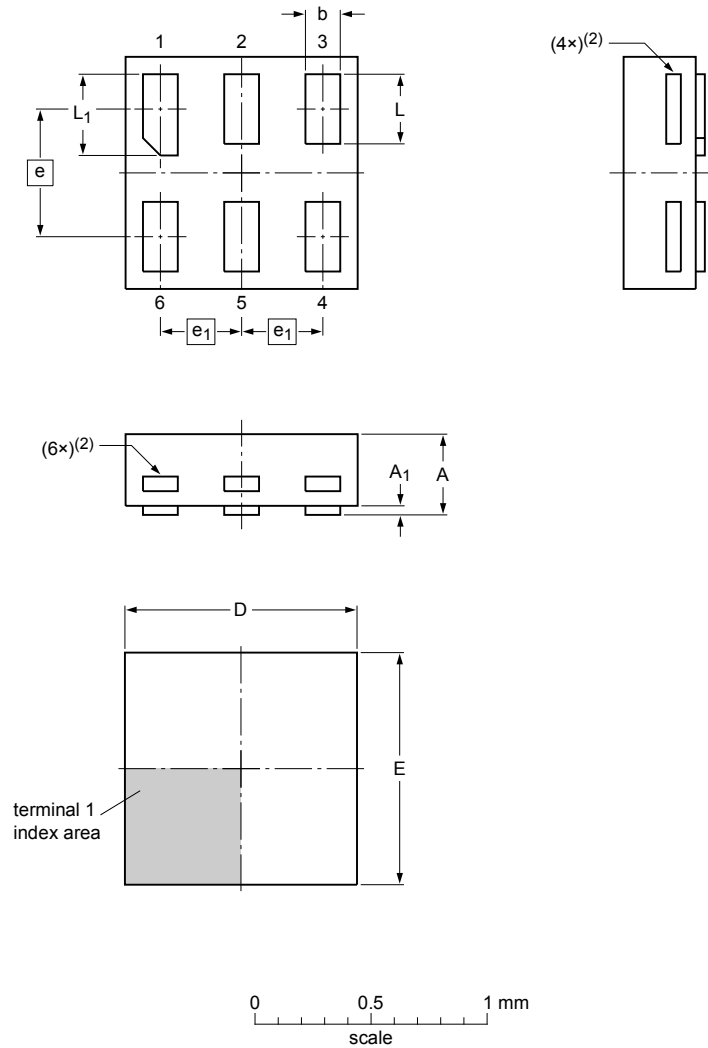


XSON6: extremely thin small outline package; no leads; 6 terminals; 6 terminals; body 1.0 x 1.0 x 0.35 mm

2. Package outline

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Dimensions

Unit	A ⁽¹⁾	A ₁	b	D	E	e	e ₁	L	L ₁
mm	max 0.35	0.04	0.20	1.05	1.05			0.35	0.40
	nom		0.15	1.00	1.00	0.55	0.35	0.30	0.35
	min		0.12	0.95	0.95			0.27	0.32

Note

- Including plating thickness.
- Visible depending upon used manufacturing technology.

sot1202_po

Outline version	References			European projection	Issue date
	IEC	JEDEC	JEITA		
SOT1202					10-04-02 10-04-06

Fig. 1. Package outline XSON6 (SOT1202)

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3. Soldering

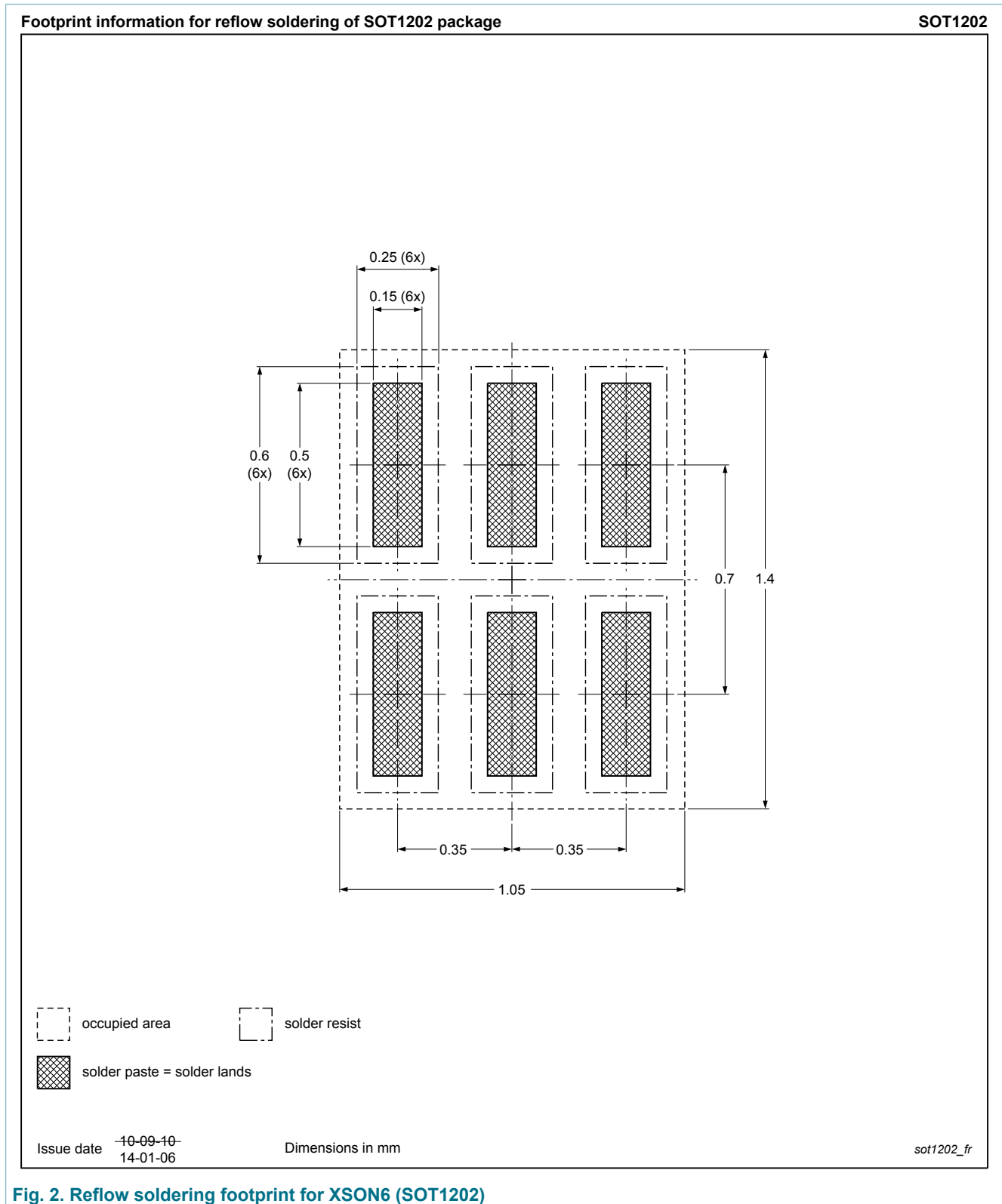


Fig. 2. Reflow soldering footprint for XSON6 (SOT1202)

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4. Legal information

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Date of release: 8 February 2016
